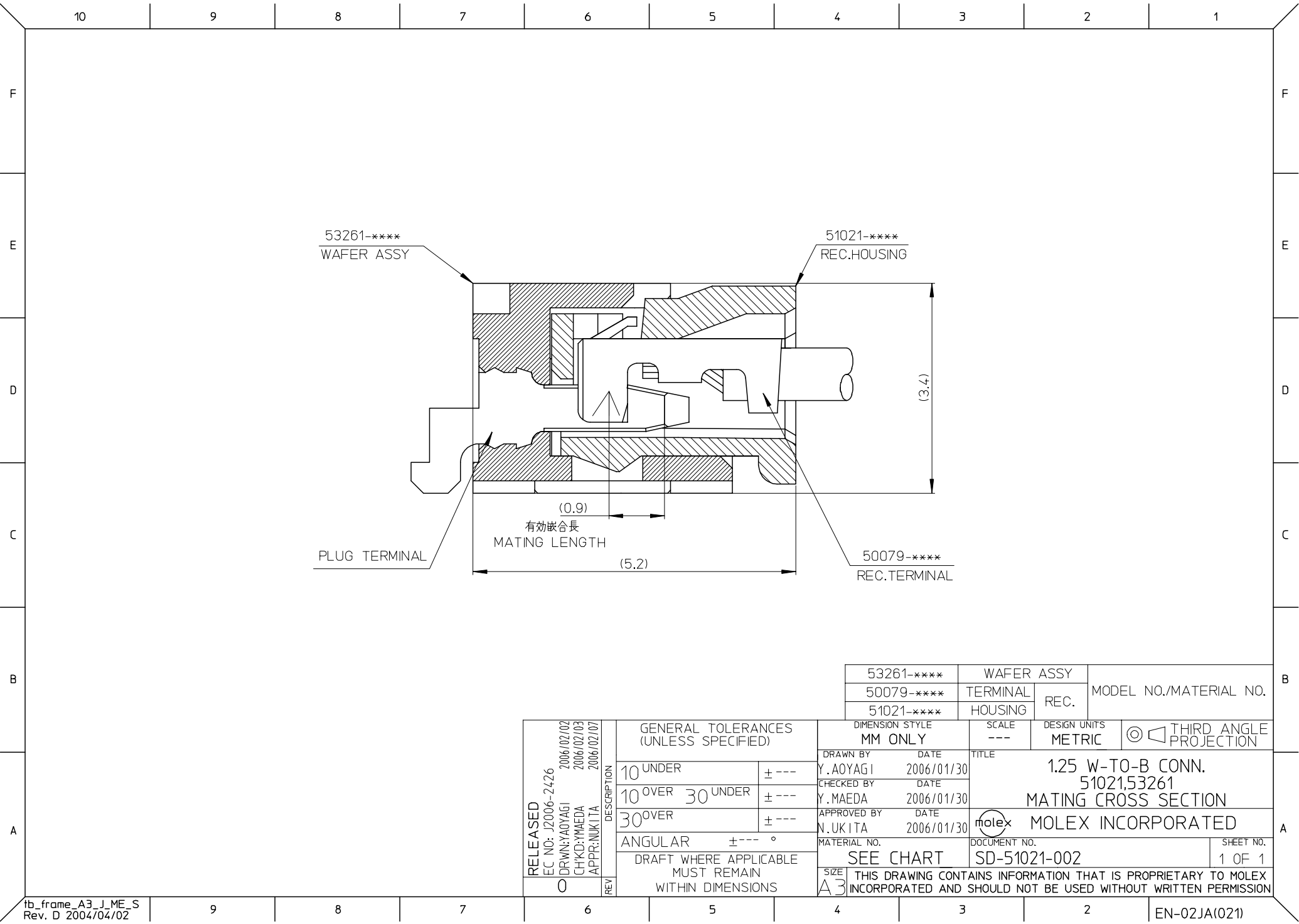
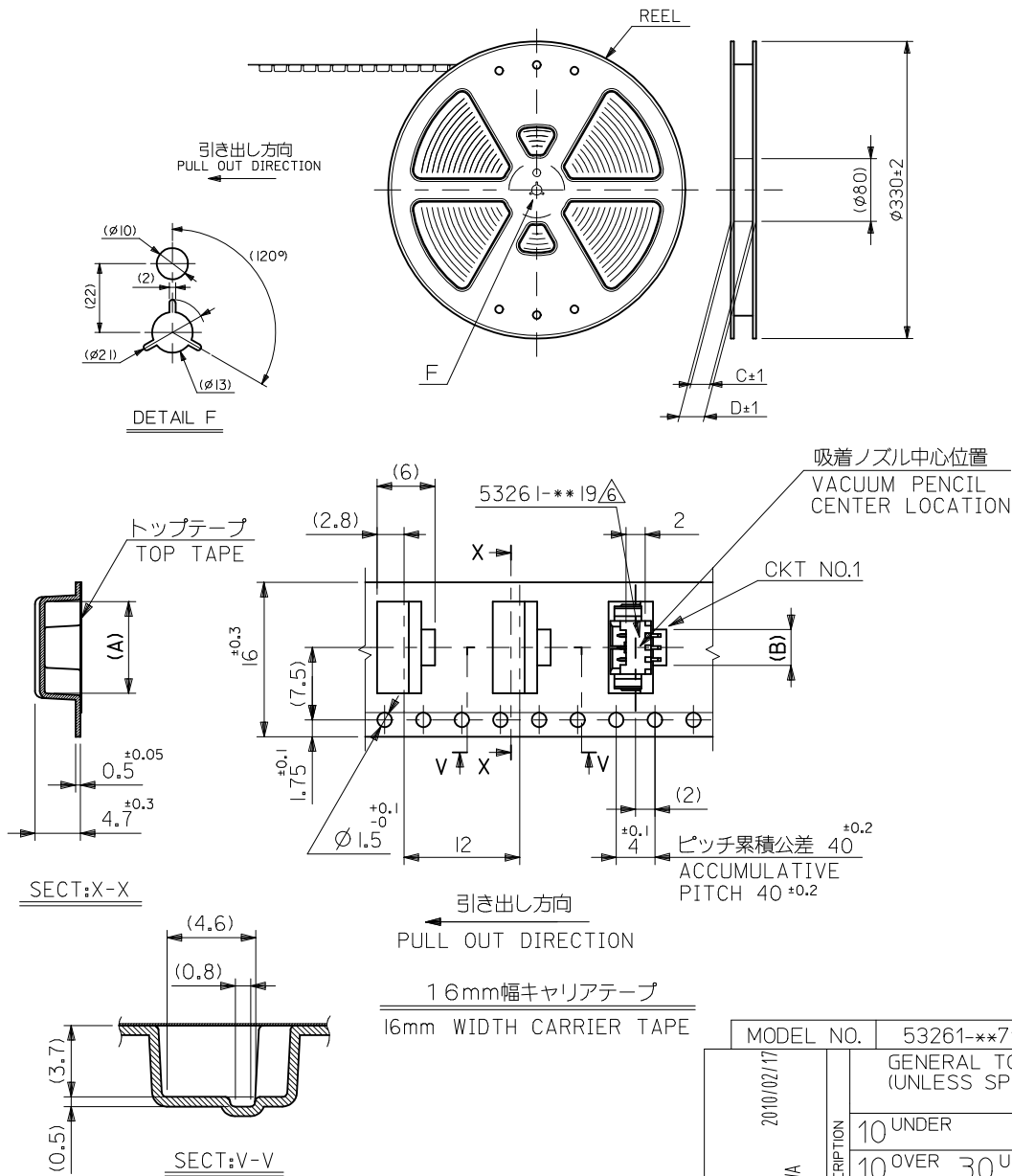




53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: YAOYAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07 REV 0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY Y. AOYAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
		10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30					
		30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO.			DOCUMENT NO.			SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART			SD-51021-002			1 OF 1
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

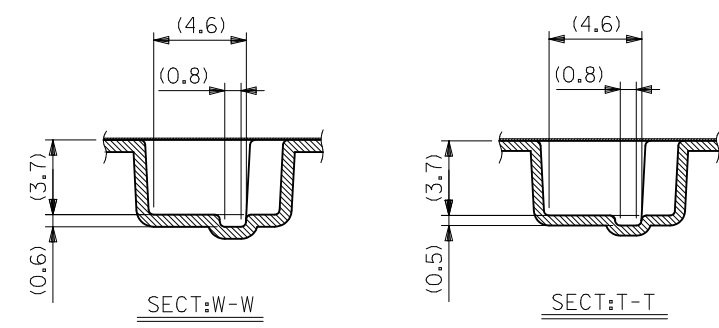
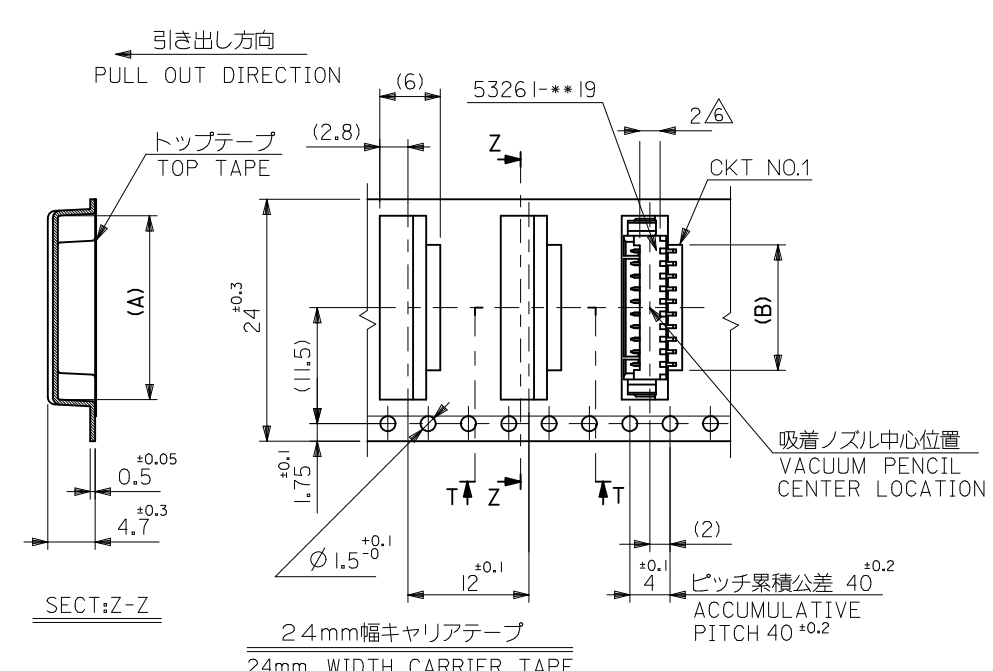
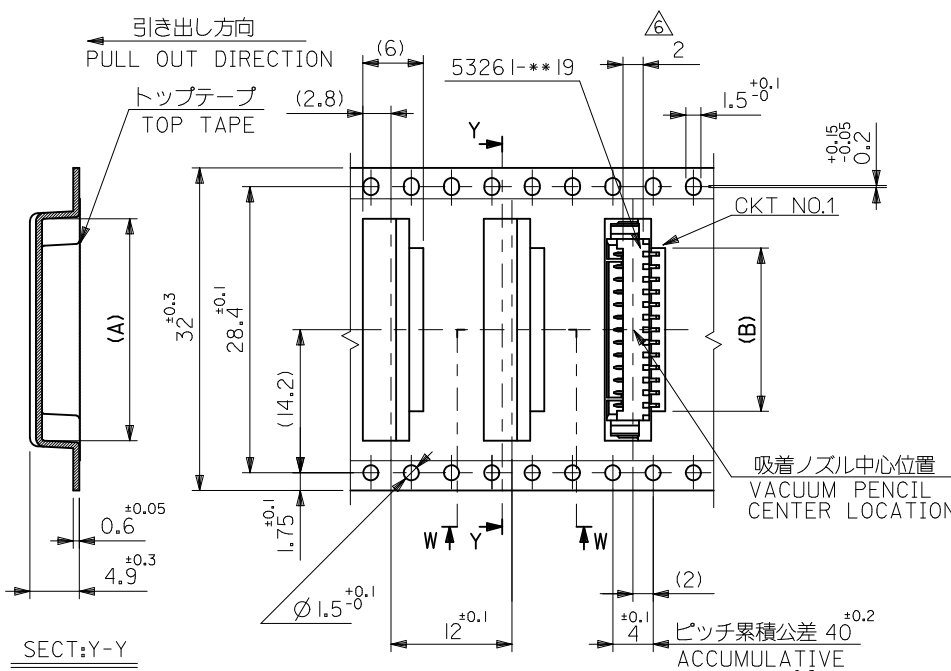
10 9 8 7 6 5 4 3 2 1



注記
NOTES

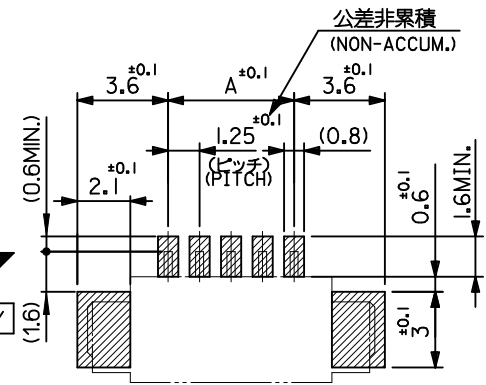
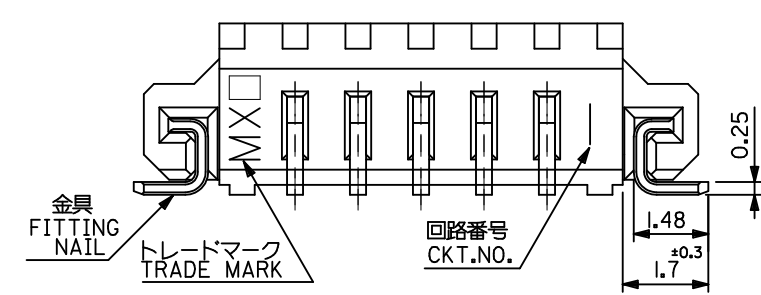
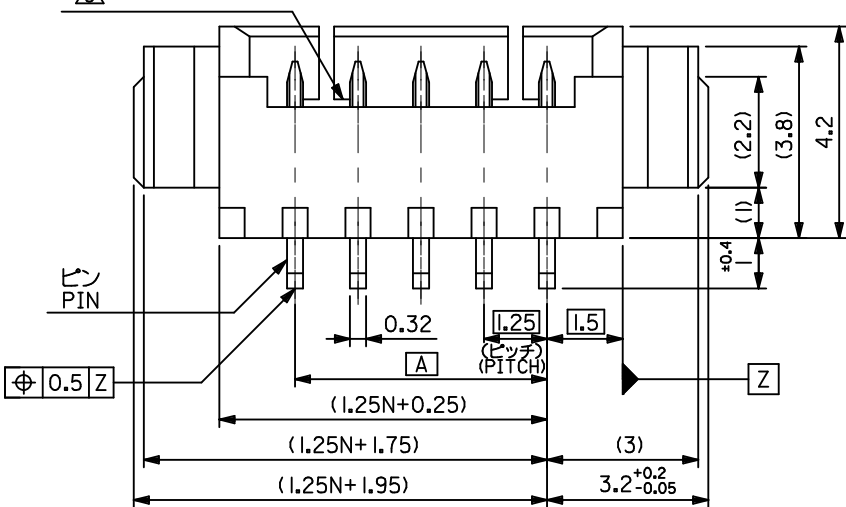
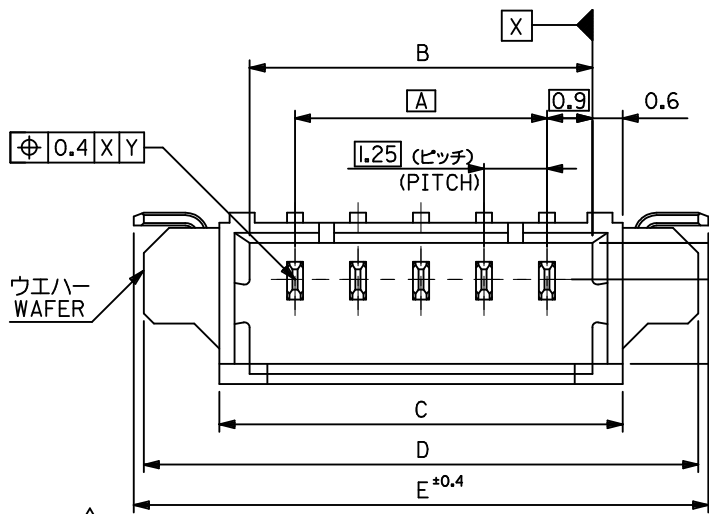
- 53261-**-19 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH
トップテープリーダー部 TOP TAPE LEADER PART
トップテープ未接着部 TOP TAPE NON-BONDED PART
175⁺²⁵ 25⁺⁵
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA
- 本製品は 53261-**-90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-90
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

16		21.4	17.4	3.7	9.5	53261-0371		3
				2.45	8.25	53261-0271		2
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.		極数 CKT.
TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY			SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
± 0.2		DRAWN BY H. SHIMABUKUR		DATE '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		
± 0.25		CHECKED BY K. TOJO		DATE '04/02/06				
± 0.3		APPROVED BY NUKITA		DATE 2010/02/18				
3 °		MATERIAL NO.			DOCUMENT NO.			SHEET NO.
APPLICABLE MAIN DIMENSIONS		SEE TABLE & SHEET 2,3			SD-53261-023			1 OF 3
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

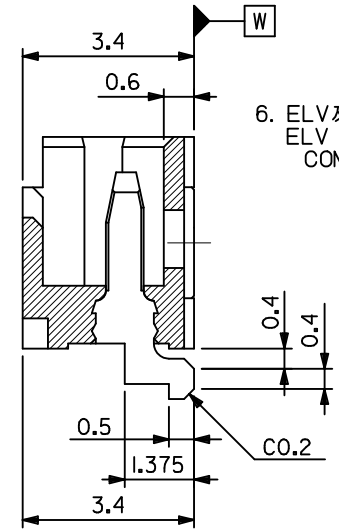


32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
			13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	53261-0471	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE	極数 CKT.
					オーダー番号 ORDER NO.	

MODEL NO.	53261-**-71	DIMENSION STYLE	MM ONLY	SCALE	---	DESIGN UNITS	METRIC	THIRD ANGLE PROJECTION
REVISED	EC NO.	DRWN:YGO10	CHKD:KASAKAWA	APPR:	2010/02/17	DESCRIPTION	10 UNDER ±0.2	10 OVER 30 UNDER ±0.25
							30 OVER ±0.3	ANGULAR ±3 °
							DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
							SIZE A3	
							THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
							DRAWN BY H. SHIMABUKUR DATE '04/02/06	
							CHECKED BY K. TOJO DATE '04/02/06	
							APPROVED BY NUKITA DATE 2010/02/18	
							MATERIAL NO. SEE TABLE & SHEET 13	
							DOCUMENT NO. SD-53261-023	
							SHEET NO. 2 OF 3	



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)
(SCALE 5:1)



【断面図】
[CROSS SECTION]

注記 NOTES

1. 嵌合相手: 51021 シリズ
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウェハー: NYLON46, UL94V-0
ピン: リン青銅
PIN: PHOS-BRO
: 銅メッキ 1.0マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0マイクロメートル以上
: NICKEL(UNDER PLATING) 1.0 MICROMETER MINIMUM
金具: リン青銅
FITTING NAIL: PHOS-BRO
: 銅メッキ 1.0マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0マイクロメートル以上
: NICKEL(UNDER PLATING) 1.0 MICROMETER MINIMUM
- △ ロック窓は2、3極は1箇所、4極以上は2箇所とする。
LOCKING WINDOW:
ONE PLACE FOR 2 AND 3 CKT. AND
TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダテール部のスレ量及び金具(補強板)のスレ量は基準面 [W] に対し、上方向 0.05 MAX.、下方向に 0.1 MAX. とする。 [W]
OFFSET BETWEEN BASIS PLANE
TO SOLDER TAIL BOTTOM AND
FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.
5. 本製品は 53261-***10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-***10

26.4	26	23	21.8	20	53261-1719	17
23.9	23.5	20.5	19.3	17.5	-1519	15
22.65	22.25	19.25	18.05	16.25	-1419	14
21.4	21	18	16.8	15	-1319	13
20.15	19.75	16.75	15.55	13.75	-1219	12
18.9	18.5	15.5	14.3	12.5	-1119	11
17.65	17.25	14.25	13.05	11.25	-1019	10
16.4	16	13	11.8	10	-0919	9
15.15	14.75	11.75	10.55	8.75	-0819	8
13.9	13.5	10.5	9.3	7.5	-0719	7
12.65	12.25	9.25	8.05	6.25	-0619	6
11.4	11	8	6.8	5	-0519	5
10.15	9.75	6.75	5.55	3.75	-0419	4
8.9	8.5	5.5	4.3	2.5	-0319	3
7.65	7.25	4.25	3.05	1.25	53261-0219	2
E	D	C	B	A	MATERIAL. NO.	極數 CKT.

REVISED EC NO: J2012-1315 2012/04/16 DRWN: NITO 2012/04/16 CHKD: KASAKAWA 2012/04/16 APPR: Y010 2012/04/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	1.25 WIRE TO BOARD WAFER ASS FOR SMT molex SD-53261-024 SHEET NO. 1 OF 1				
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06					
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06					
G	REV	ANGULAR ±3 °		MATERIAL NO. SEE DRAWING		DOCUMENT NO. SD-53261-024				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				